



Final Product Change Notification

201806003F01

Issue Date: 20-Jun-2018

Effective Date: 30-Sep-2018

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QUALITY

Management Summary

LPC8N04FHI24 Boot ROM update from version 0.12 to version 0.14 to support Over The Air (OTA) firmware update and vector checksum verification.

Change Category

- | | | | | |
|--|---|--|---|---|
| <input type="checkbox"/> Wafer Fab Process | <input type="checkbox"/> Assembly Process | <input type="checkbox"/> Product Marking | <input type="checkbox"/> Test Location | <input type="checkbox"/> Design |
| <input type="checkbox"/> Wafer Fab Materials | <input type="checkbox"/> Assembly Materials | <input type="checkbox"/> Mechanical Specification | <input type="checkbox"/> Test Process | <input type="checkbox"/> Errata |
| <input type="checkbox"/> Wafer Fab Location | <input type="checkbox"/> Assembly Location | <input type="checkbox"/> Packing/Shipping/Labeling | <input type="checkbox"/> Test Equipment | <input type="checkbox"/> Electrical spec./Test coverage |
| <input checked="" type="checkbox"/> Firmware | <input type="checkbox"/> Other | | | |

LPC8N04 Boot ROM Update to Support Over The Air (OTA)

Description of Change

The LPC8N04FHI24 Boot ROM will be updated.

- Boot ROM version number is changed from version 0.12 to version 0.14.
- Boot ROM was updated to support application vector checksum verification before booting the image.
- Users migrating from previous version need to ensure that the reserved Cortex-M0+ exception vector location 7 (offset 0x 0000 001C in the vector table) contains the 2's complement of the check-sum of table entries 0 through 6.
- Boot ROM code was updated to support OTA firmware update using Secondary Bootloader (SBL) library. See Tech Note TN00040: LPC8N04: Encrypted Over the Air (OTA) Firmware update using NFC.

The following documents are updated to support this change.

Data sheet: LPC8N04 v.1.4, <https://www.nxp.com/docs/en/data-sheet/LPC8N04.pdf>

User Manual: UM11074 v.1.2, <https://www.nxp.com/docs/en/user-guide/UM11074.pdf>

Tech Note: TN00040: LPC8N04: Encrypted Over the Air (OTA) Firmware update using NFC,

<https://www.nxp.com/docs/en/application-note/TN00040.zip?fsrch=1&sr=1&pageNum=1>

Reason for Change

To support OTA firmware update and application checksum verification.

Identification of Affected Products

Parts with date code 824 (workweek 1824) or later have firmware version 0.14. The date code can be seen on the part marking and packing labels.

Product Availability

Sample Information

Samples are available from 25-Jun-2018

Production

Planned first shipment 30-Sep-2018

Anticipated Impact on Form, Fit, Function, Reliability or Quality

No physical change to die or packaging. No Quality or Reliability impact. The user needs to include checksum verification.

Data Sheet Revision

A new datasheet will be issued

Disposition of Old Products

Products with firmware version 0.12 will no longer be shipped.

Timing and Logistics

In compliance with JEDEC J-STD-046, your acknowledgement of this change is expected by 20-Jul-2018.

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

Name Tim Camenzind
Position Senior Quality Engineer
e-mail address tim.camenzind@nxp.com

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NXP Quality Management Team.

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Changed Orderable Part#	Changed Part 12NC	Changed Part Number	Changed Part Description	Package Outline	Package Name	Status	Product Line
LPC8N04FHI24E	935359392551	LPC8N04FHI24	32-bit ARM Cortex-M0+	SOT616-3	HVQFN24	RFS	BL Microcontrollers
LPC8N04FHI24Z	935359392515	LPC8N04FHI24	32-bit ARM Cortex-M0+	SOT616-3	HVQFN24	RFS	BL Microcontrollers